

ABSTRACT OF THE DISCLOSURE

An integrated circuit device has a substrate, an interconnection level, a shielding level and a plurality of stitching studs. The substrate has a plurality of active devices, and the stitching studs pass through the substrate. The
5 interconnection level is on the substrate, having a plurality of metal lines to provide interconnections between the active devices with a plurality of plugs. The shielding level is on the interconnection level, having an electromagnetic shielding pattern. The electromagnetic shielding pattern, the plugs, and the stitching studs are connected to form an electromagnetic shielding housing of
10 the integrated circuit device.